



Reliability Redefined

# A reliable & versatile tool for micromachining

/ Glass, sapphire and ceramics micro processing

/ Microelectronics manufacturing

/ Glass intra volume structuring

/ Micro processing of different polymers and metals

/ LCD, LED, OLED drilling, cutting and repair

Zero maintenance

2 years of total warranty

# 30 W Femtosecond Industrial Laser

# FemtoLux 30

### Designed from the get-go for maximum reliability, seamless integration and non-stop 24/7/365 zero maintenance operation with innovative "dry" cooling.

The FemtoLux 30 femtosecond laser has a tunable pulse duration from <350 fs to 1 ps and can operate in a broad AOM controlled range of pulse repetition rates from a single shot to 4 MHz.

The maximum pulse energy is more than 90  $\mu$ J operating with single pulses and can reach more than 250  $\mu$ J in burst mode, ensuring higher ablation rates and processing throughput for different materials.

The FemtoLux 30 beam parameters will meet the requirements of the most demanding materials and micro-machining applications.

Innovative laser control electronics ensure simple control of the FemtoLux 30 laser by external controllers that could run on different platforms, be it Windows, Linux or others using REST API commands.

This makes easy integration and reduces the time and human resources required to integrate this laser into any laser micromachining equipment.

### Seamless User Experience

Easy integration - remote control using REST API via RS232 and LAN.

**Reduced integration time** – demo electronics is available for laser control programming in advance.

**Easy and quick installation** – no water, fully disconnectable laser head. Can be installed by the end-user.

**Easy troubleshooting** – integrated detectors and constant system status logging.

No periodic maintenance required.

### At 1030 nm 30 W

>90 uJ

At 515 nm 11 W

At 343 nm

### Features

Typical max output power 30 W at 1030 nm, 11 W at 515 nm, 6 W at 343 nm

Typical max output energies > 90 μJ at 1030 nm, > 55 μJ at 515 nm, > 30 μJ at 343 nm

**High energy** version available (**1 mJ** at 10 kHz)

MHz, GHz, MHz+GHz burst modes

> 250 µJ in a burst mode

< 350 fs – 1 ps

Single shot to 4 MHz (AOM controlled)

**Pulse-on-demand** (PoD), with jitter as low as 20 ns (peak-to-peak)

<0.5% RMS power long term stability over 100 hours

 $M^2 < 1.2$ 

Beam circularity > 0.85

Zero maintenance

Dry cooling (no water used)

2 years of total warranty



Learn more about FemtoLux 30 www.ekspla.com



# **"Dry" Cooling** Direct Refrigerant Cooling System

The FemtoLux 30 laser employs an innovative cooling system and sets new reliability standards among industrial femtosecond lasers. No additional bulky and heavy water chiller is needed.

The chiller requires periodic maintenance – cooling system draining and rinsing and water and particle filter replacement. Moreover, water leakage can cause damage to the laser head and other equipment. Instead of using water for transferring heat from a laser head, the FemtoLux 30 laser uses an innovative Direct Refrigerant Cooling method.

The refrigerant agent circulates from a PSU-integrated compressor and condenser, to a cooling plate via armored flexible lines.

The entire cooling circuit is permanently hermetically

sealed and requires no maintenance.



See **FemtoLux 30** introduction video showing "dry cooling" advantages



Military-grade reliability

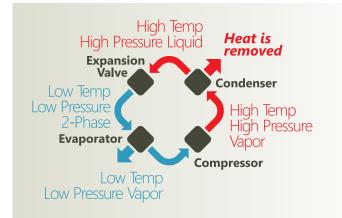
Permanently hermetically sealed system >90,000 hour MTBF

#### No maintenance

High cooling efficiency

>45% lower power consumption compared to water cooling equipment

#### **Compact and light**





Detachable cooling plate

**Integrated** cooling equipment with the laser power supply

## Simple & Reliable Cooling Plate Attachment

The cooling plate is detachable from the laser head for more convenient laser installation. The laser cooling equipment is integrated with the laser power supply unit into a single 4U rack-mounted housing with a total weight of 15 kg.





Simple and reliable cooling plate attachment

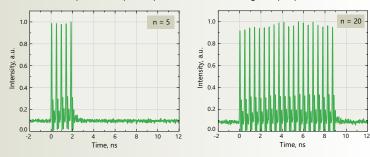


# **GHz Burst Option**

Patent-Pending Method for Ultra-High Rate Bursts

### Short GHz burst

**Fig 1.** Measured 2.2 GHz intra-burst PRR burst of pulses containing a different number of pulses of equal amplitudes at 31.5 W average output power



### Long GHz burst

**Fig 2.** Measured 2.2 GHz pre-shaped bursts of 1000 pulses at 233 kHz burst repetition rate for the desired rectangular-like burst shape

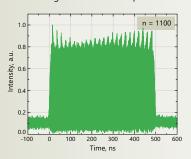
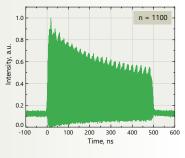


Fig 3. Measured 2.2 GHz non-pre-shaped bursts of 1100 pulses at 233 kHz burst repetition rate



### MHz + GHz burst mode

**Fig 4.** Measured 4 bursts of 50 MHz BRR containing 4 pulses of 2.5 GHz intra-burst PRR

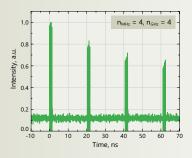
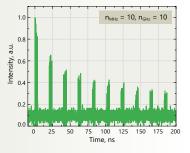


Fig 5. Measured 10 bursts of 50 MHz BRR containing 10 pulses of 2.5 GHz intra-burst PRR



### Benefits

The Femtolux 30 laser can operate in the **single-pulse** mode, **MHz burst** mode and **GHz burst** mode.

The burst formation technique based on the use of the AFL is a very versatile method as it allows to overcome many limitations encountered by other fiber- and/or solid-statebased techniques.

### Any desired intra-burst PRR

**can be achieved** independently from the initial PRR of the master oscillator

### Identical pulse separation

inside the GHz bursts is maintained

# Short- and long-burst formation modes can be provided.

/ A short burst is up to about10 ns burst width (from 2 to tens of pulses in the GHz burst).

/ A long burst is from ~20 ns up to a few hundred ns in burst width (from tens to thousands of pulses in the GHz burst)

#### MHz+GHz burst mode

An adjustable amplitude envelope of the GHz bursts is provided

**No pre/post pulses** in GHz burst. Pure GHz bursts

**Ultrashort pulse duration** is maintained inside the bursts



# A new versatile patent-pending method to form ultra-high repetition rate bursts of ultrashort laser pulses.

The developed method is based on the use of an all-in-fiber active fiber loop (AFL). A detailed description of the invention can be found on:

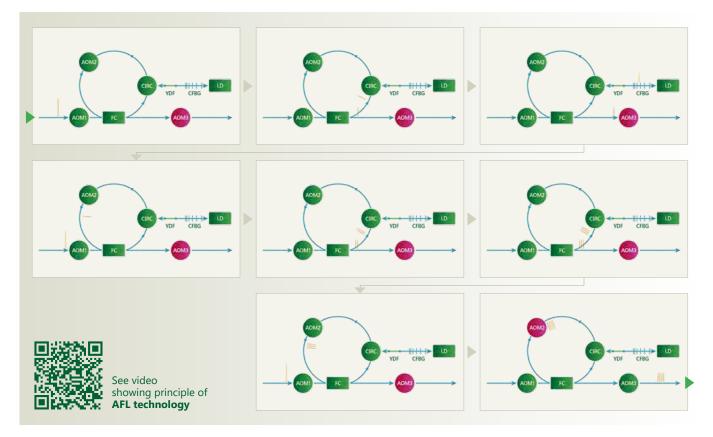
[1] Andrejus Michailovas, and Tadas Bartulevičius. 2021 Int. patent application published under the Patent Cooperation Treaty (PCT) WO2021059003A1.

[2] Tadas Bartulevičius, Mykolas Lipnickas, Virginija Petrauskienė, Karolis Madeikis, and Andrejus Michailovas, (2022), "30 W-average-power femtosecond NIR laser operating in a flexible GHz-burst-regime," Opt. Express 30, 36849-36862.

# Specifications

Parameter	Value			
Burst repetition rate	200 – 650 kHz			
Intra-burst pulse repetition rate <sup>1)</sup>	2 GHz			
GHz burst mode	short	long		
Number of pulses <sup>2)</sup>	2 – 22	44 – 1100		
Shape	square, rising, falling	falling, pre-shaped <sup>3)</sup>		
MHz + GHz burst mode				
Burst repetition rate	100 – 650 kHz	100 – 650 kHz		
Number of pulses in MHz burst	2 – 10			
Number of pulses in GHz burst	2 – 22			
<ul> <li><sup>9</sup> Custom intra-pulse PRR is available upon a request.</li> <li><sup>20</sup> Depends on the intra-pulse PRR.</li> <li><sup>30</sup> For more information, please inquire sales@ekspla.com.</li> </ul>				

### Principle of AFL Technology



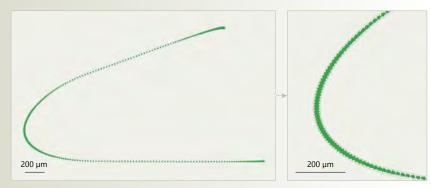


# Pulse-on-Demand (PoD)

Traditional laser triggering techniques struggle to maintain equally spaced pulses at high speeds (Fig.1, 2). Pulse-on-demand feature tackles this challenge and enables high-speed micromachining (Fig. 3).

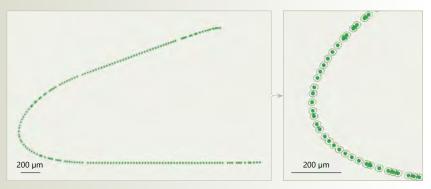
#### Time based laser triggering

**Fig 1.** Complex shape scanned with time based laser triggering mode with a pulse repetition of 200 kHz and scanning speed of 6 m/s. The scanning started from the top right to the bottom right area. Overlapping pulses result in an overheated area.



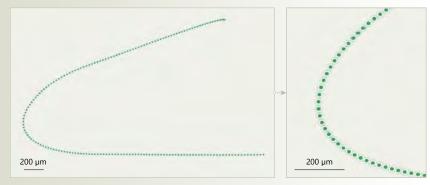
#### Position based laser triggering

**Fig 2.** Complex shape scanned with position based laser triggering mode with a pitch of 30  $\mu$ m and scanning speed of 6 m/s. The scanning started from the top right to the bottom right area. Jitter of tens of  $\mu$ s results in random pulse spacing.



### Pulse-on-demand (PoD)

Fig 3. Complex shape scanned with pulse-on-demand (PoD) and position based laser triggering mode with a pitch of 30  $\mu m$  and scanning speed of 6 m/s. The scanning started from the top right to the bottom right area. PoD feature preserves equidistant pulse spacing at high speeds.



## Benefits

Jitter lower than 20 ns ensures consistent and equidistant pulse spacing for high-speed micromachining

Adjustable repetition rate for processing complex geometries

Faster processing speeds, increased productivity

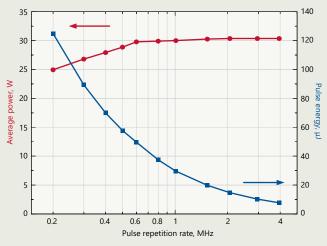
PoD feature enables the laser to fire a pulse only when required, rather than at a constant rate, enabling precise control over the laser's output and resulting in higher efficiency, accuracy and quality.

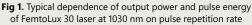
This capability is especially valuable in various micromachining applications where a high processing speed, constant energy, and accuracy are essential. To follow complex curvature at high speed and to maintain equidistant spacing it is necessary to ensure tha the repetition rate of the pulses is adjusted. To achieve these requirements, it is necessary to ensure that the repetition rate of the pulses is adjusted to follow complex curvature at high speed and to maintain equidistant spacing. One may try to use position based laser triggering but, due to laser system limitations, the jitter will be from several µs to tens of µs, which will result in random spacing of the pulses. On the other hand, the usage of time based laser triggering results in overheat areas, due to excessive overlap of pulses. The FemtoLux 30 laser has the pulse-on-demand feature with jitter as low as 20 ns (peak-to-peak), and it can therefore tackle all the challenges and maximize process efficiency, precision and quality at high speed.

# Specifications <sup>1)</sup>

Model		FemtoLux 30			
Main specifications					
	fundamental		1030 nm		
Central wavelength	with second harmor	nic option	515 nm		
	with third harmonic		343 nm		
Pulse repetition rate (PRR) <sup>2)</sup>		200 kHz – 4 MHz			
Pulse repetition frequency (PRF) after frequency divider		PRF = PRR / N, N=1, 2, 3, , 65000; single shot			
Average output power	at 1030 nm		> 27 W (typical 30 W)	<u> </u>	
	at 515 nm		> 11 W <sup>3</sup> )		
	at 343 nm		> 6 W <sup>3)</sup>		
Pulse energy	at 1030 nm		> 90 µJ or 1 mJ 4)		
	at 515 nm		> 55 µJ <sup>3)</sup>		
	at 343 nm		> 30 µJ <sup>3)</sup>		
Number of pulses in MHz burst <sup>5)</sup>		2 - 10			
Total energy in burst mode		> 250 µJ <sup>6)</sup>			
Power long term stability (Std. dev.) <sup>7)</sup>		< 0.5 %			
Pulse energy stability (Std. dev.) <sup>8</sup>		<1%			
Pulse duration (FWHM)		tunable, < 350 fs <sup>9)</sup> – 1 ps <sup>10)</sup>			
Beam quality		M <sup>2</sup> < 1.2 (typical < 1.1)			
Beam circularity, far field		> 0.85			
Beam divergence (full angle)		< 1 mrad			
Beam pointing thermal stability		< 20 µrad/°C			
Beam diameter (1/e <sup>2</sup> ) at 20 cm distance from laser aperture at 1030 nm		2.5 ± 0.4 mm			
Triggering mode		internal / external			
Pulse output control		frequency divider, pulse picker, burst mode, packet triggering, power attenuation, pulse-on-demand <sup>11)</sup>			
Control interfaces	Control interfaces		RS232 / LAN		
Length of the umbilical cord		3 m, detachable			
Laser head cooling type		dry (direct refrigerant cooling through detachable cooling plate)			
Physical characteristics					
Laser head (W $\times$ L $\times$ H)		429 × 569 × 130 mm			
Power supply unit (W $\times$ L $\times$ H)		449 × 376 × 177 mm			
Operating requirement	s				
Mains requirements		100 – 240 V AC, single phase, 50/6	0 Hz		
Operating ambient temperature		18 – 27 °C			
Relative humidity		10-80 % (non-condensing)			
Air contamination level		ISO 9 (room air) or better			
<ul> <li>Due to continuous improvement, to change without notice. Parame specifications. They are indications will vary with each unit we manufa specified for a shortest pulse dura</li> <li>When frequency divider is set to t controllable by integrated AOM.</li> <li>At 200 kHz.</li> <li>At 10 kHz, fixed pulse duration (fo</li> <li>Oscillator frequency ~50 MHz, ~2 pulses.</li> </ul>	ters marked typical are not s of typical performance and acture. All parameters are titon. ransmit every pulse. Fully r example 1 ps).	at 100 kHz PRR. > 9 7) Over 100 h after wa environmental conc 8) Under constant env 9) At PRR > 500 kHz. , duration is < 400 fs 10) Custom pulse durat 50 fs available.	litions. ironmental conditions. At PRR < 500 kHz shortest pulse	DANGER: VISIBLE AND/OR INVISIBLE LASER RADIATION AVOID EYE OR SINN EXPOSURE TO DIRECT, REFLECTED OR SCATTERD RADIATION CLASS 4 LASER PRODUCT	

### Performance





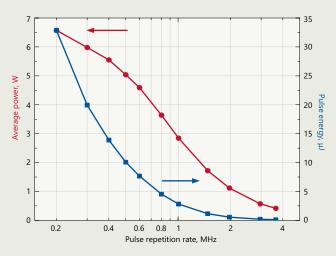
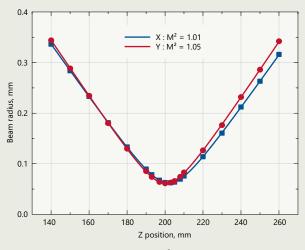


Fig 3. Typical dependence of output power and pulse energy of FemtoLux 30 laser at 343 nm on pulse repetition rate



**Fig 5.** Typical M<sup>2</sup> measurement of FemtoLux 30 laser at 1030 nm

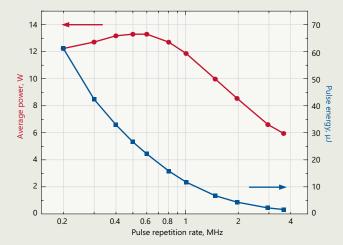


Fig 2. Typical dependence of output power and pulse energy of FemtoLux 30 laser at 515 nm on pulse repetition rate

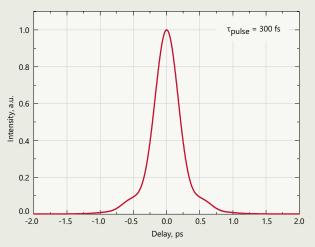
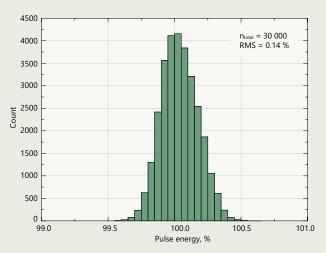
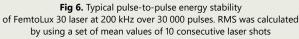


Fig 4. Typical FemtoLux 30 laser (at 1030 nm) output pulse autocorrelation function





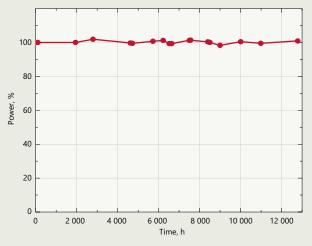


Fig 7. Long-term average power stability of the FemtoLux 30 laser at 1030 nm under constant environmental conditions over an extended duration of 12,000 hours

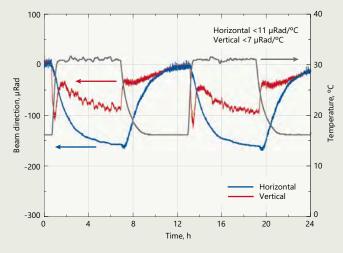


Fig 9. Typical beam direction stability of FemtoLux 30 under harsh environmental conditions

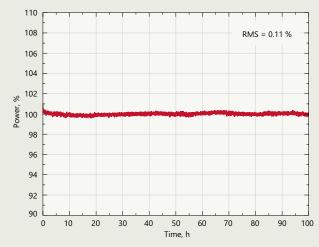


Fig 8. Typical long term average power stability of FemtoLux 30 laser at 1030 nm under constant environmental conditions

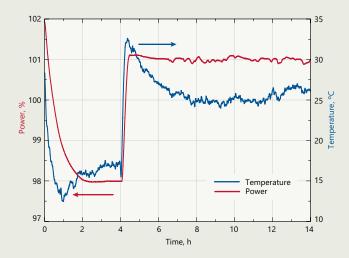


Fig 10. Average output power dependance of FemtoLux 30 laser on ambient temperature at 1030 nm



FemtoLux 30 with harmonics module and power supply



# Drawings

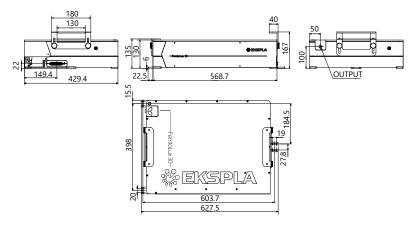


Fig 11. FemtoLux 30 laser head outline drawing

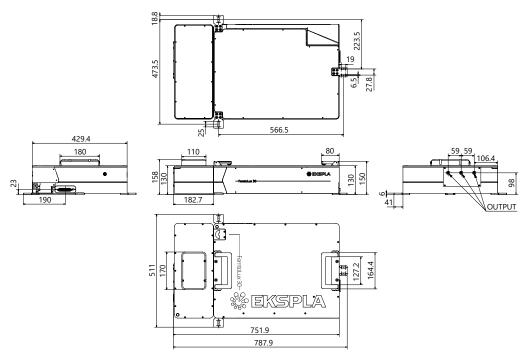


Fig 12. FemtoLux 30 with harmonics module. Laser head outline drawing

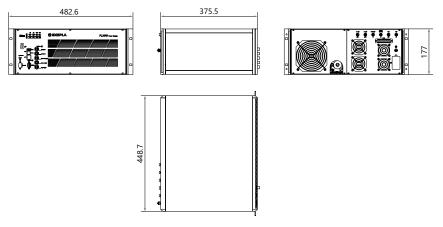


Fig 13. Power supply outline drawing



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LOTIS TII



Nd:YAGU-J-, Ti:SU-J-OPOV-5-

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